

AB stereo headphone amplifier

ILA1308D is an integrated class-AB stereo headphone amplifier with bipolar supply voltage and low value non-linear distortion of audio signal. This IC is used in modern stereo audio devices with built-in output to stereo headphones.

Performed functions: The suppression of "clicks" effect at switching on-off of the integrated circuit (IC) and power supply ripple rejection.

This IC is designed for devices with low current consumption and includes a scheme of short-circuit protection of output.

This IC consists of two separate amplifiers A and B.
IC is available in 8-pin SO-8 package (MS-012AA).

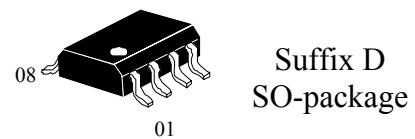


Fig 1 – View of IC in SO-package MS-012AA

Main features:

- Supply voltage

- unipolar, U_{DD}	3,0 ... 7,0 V
- bipolar, U_{DD}, U_{SS}	$\pm 1,5 \dots \pm 3,5$ V
- Consist of two separate amplifiers A & B
- Fabricated in Complementary Metal Oxide Semiconductor (CMOS) technology
- Contain short-circuit protection of output
- Low current consumption
- Operating temperature range from minus 10 to plus 85 °C

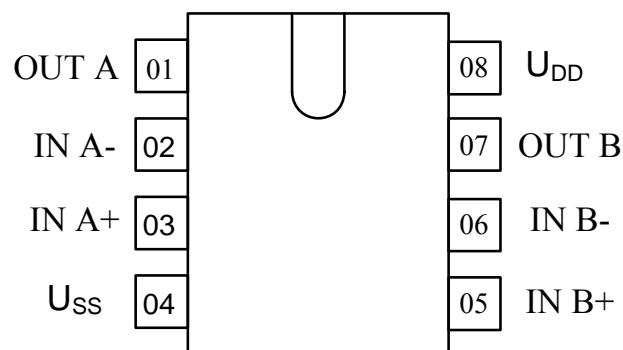
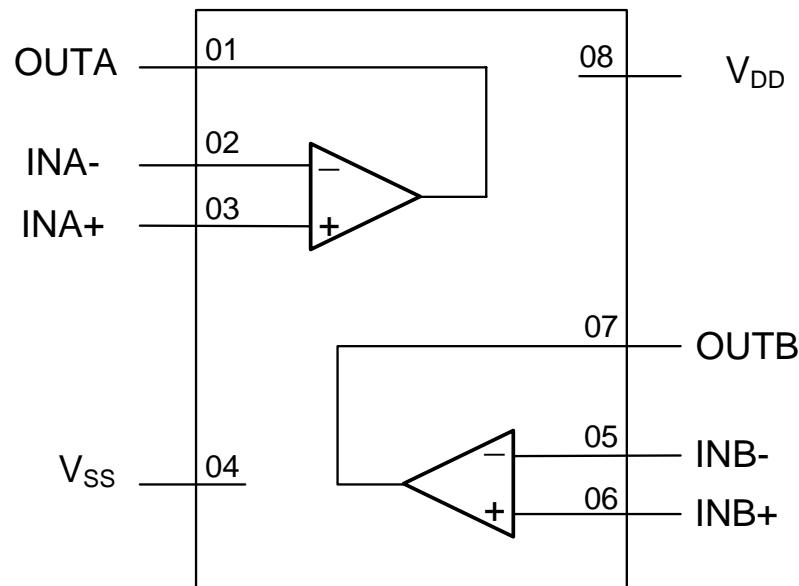


Fig. 2 – Pin layout

**Fig. 3 – Block diagram****Table 1 – Pin description**

Pin number	Symbol	Description
01	OUTA	Output A
02	INA-	Inverting input A
03	INA+	Non-inverting input A
04	V _{SS}	Negative power supply
05	INB+	Non-inverting input B
06	INB-	Inverting input B
07	OUTB	Output B
08	V _{DD}	Positive power supply

Table 2 – Absolute maximum ratings

Symbol	Parameter	Norm		Unit
		Min	Max	
U _{DD}	Supply voltage - unipolar	0	8,0	V
U _{DD} , U _{SS}	- bipolar	-	±4,0	V
T _a	Ambient temperature	-40	85	°C

Table 3 – Recommended application mode

Symbol	Parameter	Norm		Unit
		Min	Max	
U _{DD}	Supply voltage - unipolar	3,0	7,0	V
U _{DD} , U _{SS}	- bipolar	±1,5	V	V
C _L	Load capacitance	-	200	pF
P _O	Max output power at U _{CC} = 5,0 V, U _{SS} = 0 V, THD < 0,1 %, U _{O_PP} = 3,5 V	-	80	mW
T	Ambient operating temperature range	-10	85	°C



Table 4 – Electric parameters (U_{DD} = 5,0 V, U_{ss} = 0 V, f = 1kHz, R_L = 32Ω, unless otherwise specified.)

Symbol	Parameter	Test conditions	Norm		Ambient temperature	Unit
			Min	Max		
I _{DD}	Consumption current	No load	–	<u>5,0</u> 10	<u>25±10</u> –10; 85	mA
P _{tot}	Total dissipation	No load	–	<u>25</u> 35		mW
U _{CM}	Common mode voltage	–	<u>0</u> 0,5	<u>3,5</u> 3,0		V
(THD+N)/S	Total non-linear distortion of signal	U _{O PP} = 3,5 V	–	<u>–65</u> –45		dB
S/N	Signal/noise ratio	U _{O PP} = 3,5 V	<u>100</u> 60	–		dB
U _{os}	Zero bias voltage	–	–16	16	25±10	mV
G _v	Open-loop voltage gain	R _L = 5 kΩ	50	–		dB

Note – U_{O PP} – output voltage swing

Reference data

Input capacitance for normal conditions 3 pF ± 50 % at U_{DD} = 5,0 V, U_{ss} = 0 V.

Output voltage for normal conditions and V_{DD}= 5,0V, V_{ss}=0V is:

- from 0,75 to 4,25 V at R_L = 32 Ω;
- from 1,5 to 3,5 V at R_L = 16 Ω;
- from 0,1 to 4,9 V at R_L = 5 kΩ, U_{DD} = 5,0 V, U_{ss} = 0 V.

Table 5 – Typical parameters values $U_{DD} = 5,0 \text{ V}$ (U_{SS} = 0 V, f = 1kHz, R_L = 32 Ω, Ta = (25±10) °C, unless otherwise specified)

Parameter, unit	Symbol	Test conditions	Typical value*
Power supply rejection ratio , dB	PSRR	F _i = 100 Hz U ripple _{PP} = 100 mV	90
Unity gain frequency, MHz	t _G	R _L = 5 kΩ	5,5
Bandwidth , kHz	B	–	20
Output resistance, Ω	R _O	–	0,25
Channel separation, dB	a _S	R _L = 32 Ω R _L = 5 kΩ	70 105
Slew rate, V/μs, not less	SR	–	5
Max output current, mA	I _O	THD < 0,1 %	60
Input current, pA	I _B	–	10

* Typical value means normal value of parameter measured on sampling of ICs

Notes

1. U ripple_{PP} – ripple voltage swing
2. F_i – ripple frequency of supply voltage



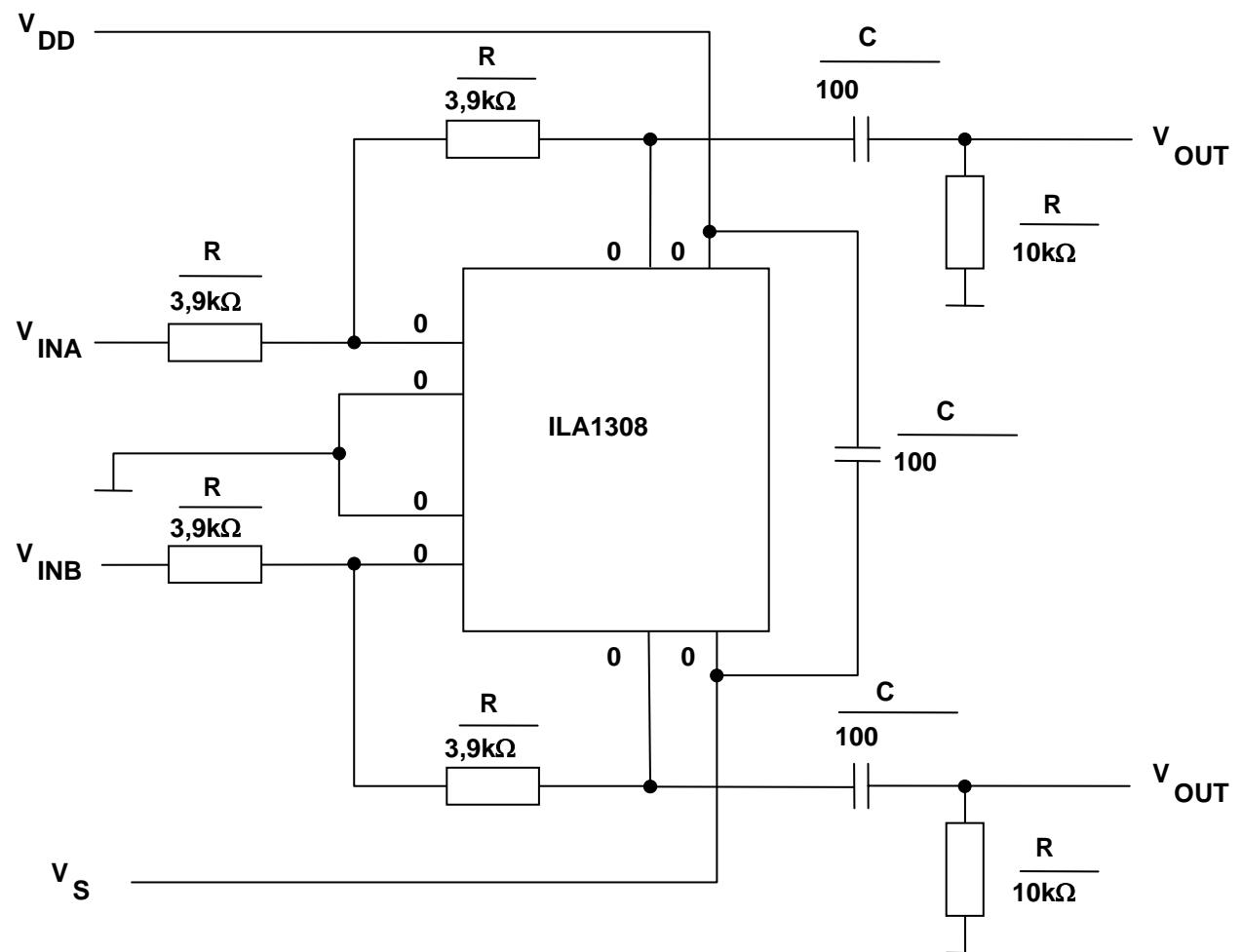
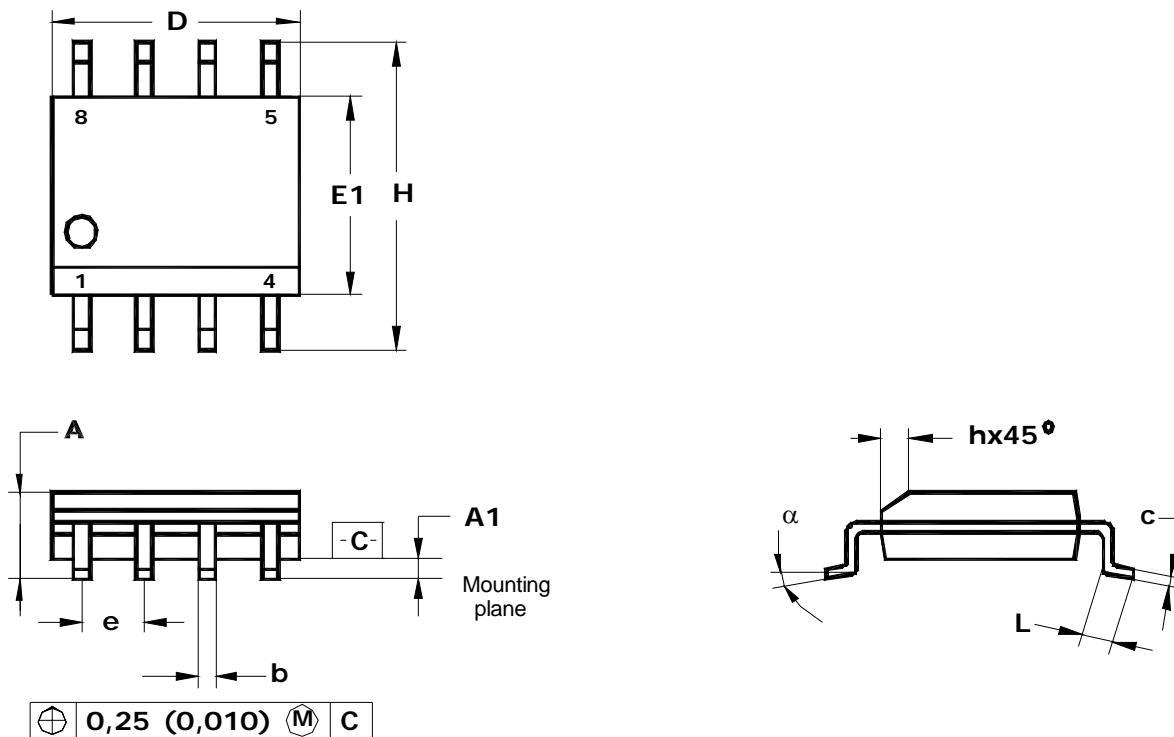


Fig. 4 – Typical application diagram

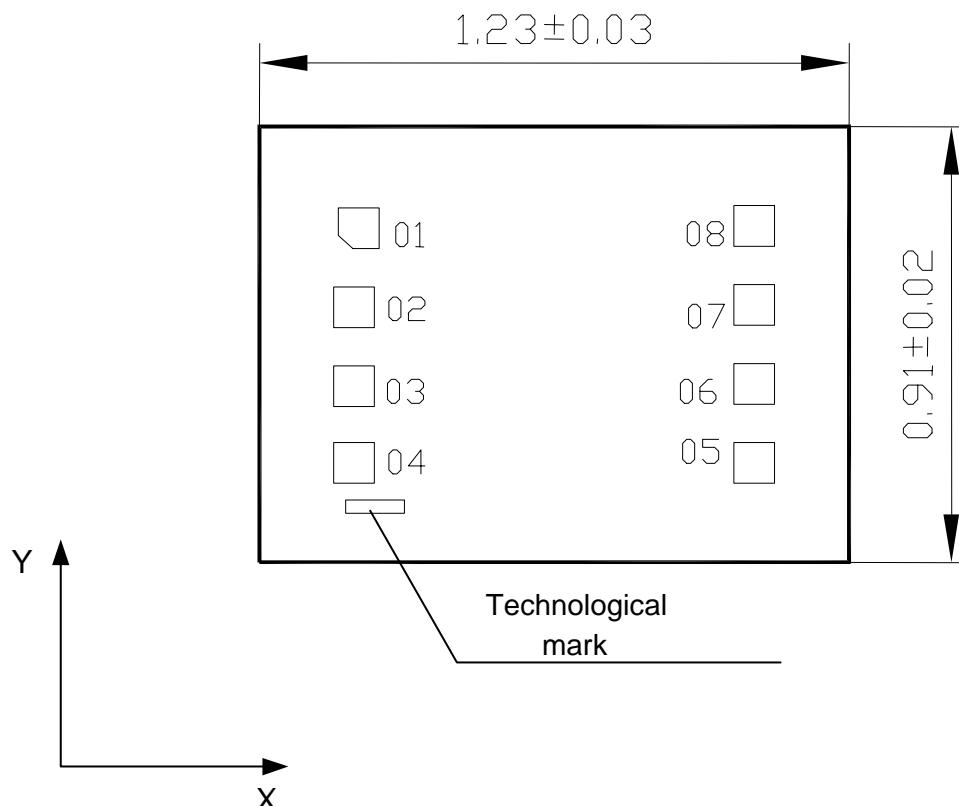
**D SUFFIX PLASTIC SOP
(MS-012AA)**



Note - Dimensions D, E1 not include burr value which has not to exceed 0,25 mm (0,010) each side.

	D	E1	H	b	e	α	A	A1	c	L	h
mm											
min	4.80	3.80	5.80	0.33		0°	1.35	0.10	0.19	0.41	0.25
max	5.00	4.00	6.20	0.51	1.27	8°	1.75	0.25	0.25	1.27	0.50
inches											
min	0.1890	0.1497	0.2284	0.013		0°	0.0532	0.0040	0.0075	0.016	0.0099
max	0.1968	0.1574	0.2440	0.020	0.100	8°	0.0688	0.0090	0.0098	0.050	0.0196

Fig. 5 - SO-package (MS-012AA) dimensions



Technological mark 1308 coordinates (mm): left bottom corner $x = 0,18$, $y = 0,13$
Die thickness $0,46 \pm 0,02$ mm.

Contact pad number	Coordinates (left bottom corner), mm	
	X	Y
01	0,165	0,655
02	0,155	0,490
03	0,155	0,325
04	0,155	0,165
05	0,990	0,165
06	0,990	0,330
07	0,990	0,495
08	0,990	0,660

Note – Note: Contact pad coordinates and size ($0,085 \times 0,085$ mm) are indicated under «Passivation» layer

Fig. 6 – Chip and contact pad layout